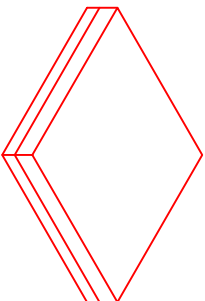


INVESTIGATION HISTORY			
REF	DESCRIPTION	DATE	REMARKS
00	INITIAL RELEASE PER DCN C06191	05/18/99	G.S.
01	REMOVED L-FIDUCIALS PER DCN C06706	10/28/99	G.S.



7. REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001-0531-2234. PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001-0519-2062. MARKING.
 6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 5. PARALLELISM IS REQUIRED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
 4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BUMPS IS 64.
 3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 8 X 8.
 2. THE BASIC SOLDER BUMP GRID PITCH IS 0.80.
 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

[illegible]